

A background image showing a Ferrari pit crew in red uniforms and helmets working on a red Ferrari Formula 1 car. A digital timer at the top displays '1.8 SEC' in red. The car has 'AI' and 'G2C' branding.

The Top Assisting Partner in the AI Supply Chain

*Empowering the success of clients across different ecosystems
through high-level collaboration*

CSUN 志聖工業
2026 Q2 Investor's meeting

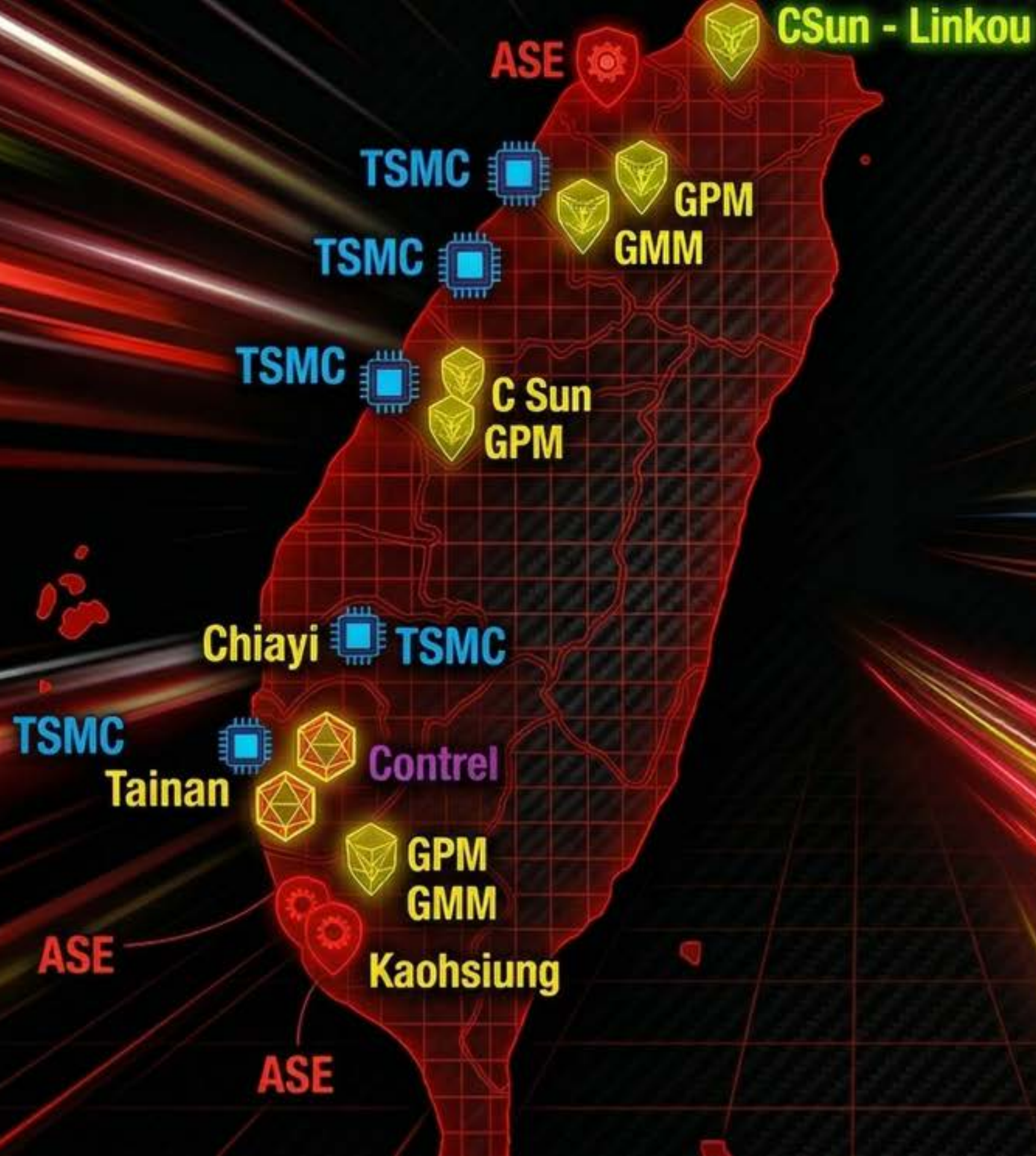
Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+ Alliance

Cross Holding Structure





FLEXIBILITY **TELEMETRY**

PRODUCTION HINTERLAND: BUILDING RESILIENCE

CONSOLIDATING 10,000-PING SPACE AT TSP & SHUGU: DELIVERING FLEXIBLE, GIANT-SCALE AUTOMATION & ASSEMBLY CAPACITY FOR THE ALLIANCE.

AUTOMATION **FLEXIBILITY** **TELEMETRY**

RAPID CO-development Network

ESTABLISHING LOCAL ZERO-DELAY SUPPORT MECHANISM: PROXIMITY SERVICE TO KEY ACCOUNTS, ENSURING STABLE HIGH-END EQUIPMENT OPERATION & JOINT DEVELOPMENT.

ZERO-TIME DEVELOPMENT SYNC



G2C+ Alliance: The Platform Advantage

Contrel (東捷)

- Laser Application (雷射應用)
- Sputtering & Dry Etching (真空濺鍍 & 乾蝕刻)

GMM (均華)

- Die Attach (黏晶)
- Chip Sorter (揀晶)

2,400+

聯盟總人數
(Total Alliance Workforce)

900+

研發人員
(R&D Personnel)

CSun (志聖)

- Thermal (熱)
- Bonder (壓合)
- Lamination (貼膜)
- Wet Process (濕製程)
- Peeling (撕膜)
- UV/Plasma (光/電漿)

GPM (均豪)

- AOI (檢測)
- Metrology (量測)
- Grinding (研磨)
- Polishing (拋光)

Professional Collaborative Team on the **AI** Track

Continuous Recognition from
Champion Team



2023:
Excellent Production Support
(卓越量產支援)



2024:
Outstanding Improvement
(傑出持續改善)

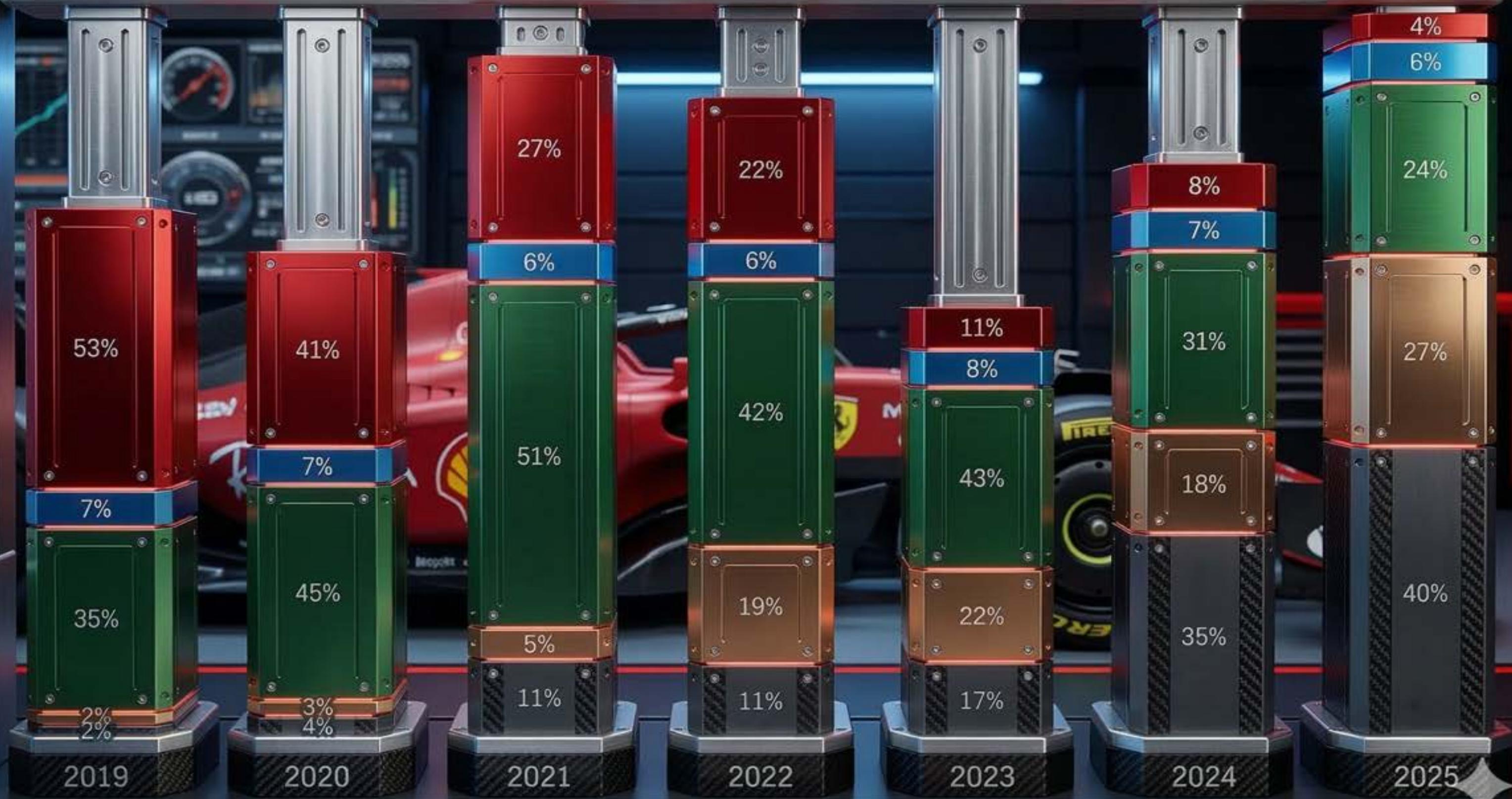


2025:
Excellent Production Support
(卓越量產支援)



REVENUE COMPOSITION (2019-2025)

7,000 —
5,000 —
4,000 —
3,000 —
2,000 —



■ FPD
 ■ Other Electronics
 ■ PCB
 ■ Advanced PCB
 ■ SEMI

2025 Financial Highlights: Structural Transformation & Record Highs

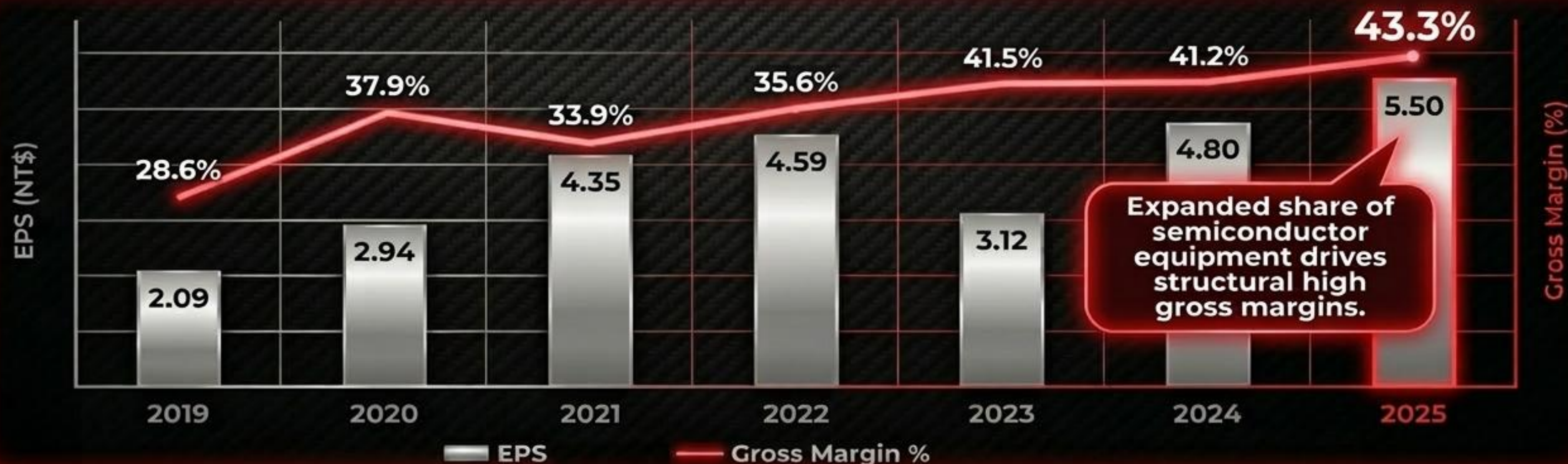
2025 Revenue

NT\$ 6.1 Billion

Record High

2025 EPS

NT\$ 5.50



R&D Resource Allocation & Tech Upgrade

Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain



Investments during the tech upgrade phase will support growth momentum for the next 3-5 years.

2026 Opening: Record-High Cumulative Revenue

**QoQ
+29.5%**

QoQ

2,262

NT\$ Million

YoY

**YoY
+72.8%**

Customers' CAPEX continues to flow in, providing sustainable momentum for future growth.

Dynamically aligning with customers' delivery schedules.





TSMC, intel, GF
FOUNDRY ACCESS TRACK

OSAT
ACCESS TRACK

AI SUBSTRATE & HDI
ACCESS TRACK

Advanced Packaging
GRAND CIRCUIT

GRAND CIRCUIT

InFO SolC EMIB X-CUBE WMCM

Adv. PLP SolC InFO

ABF HDI

SAP mSAP

FlipChip

FoCoS

FoPLP

CoWoS

CoWoS

CoWoP

CoWoP

CoWoS

mSAP

TINPAC

C SUN & G2C+

'DRIVING GROWTH THROUGH STRATEGIC EVOLUTION'

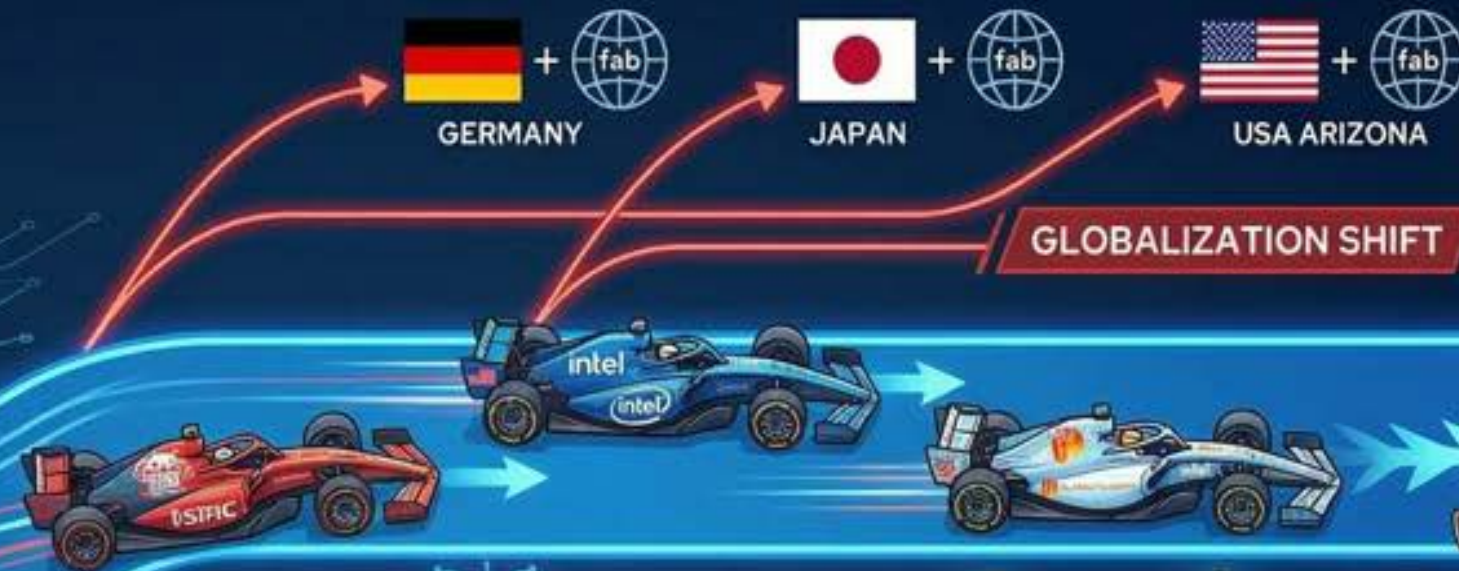
PIT STOP & COMMON STARTING GRID



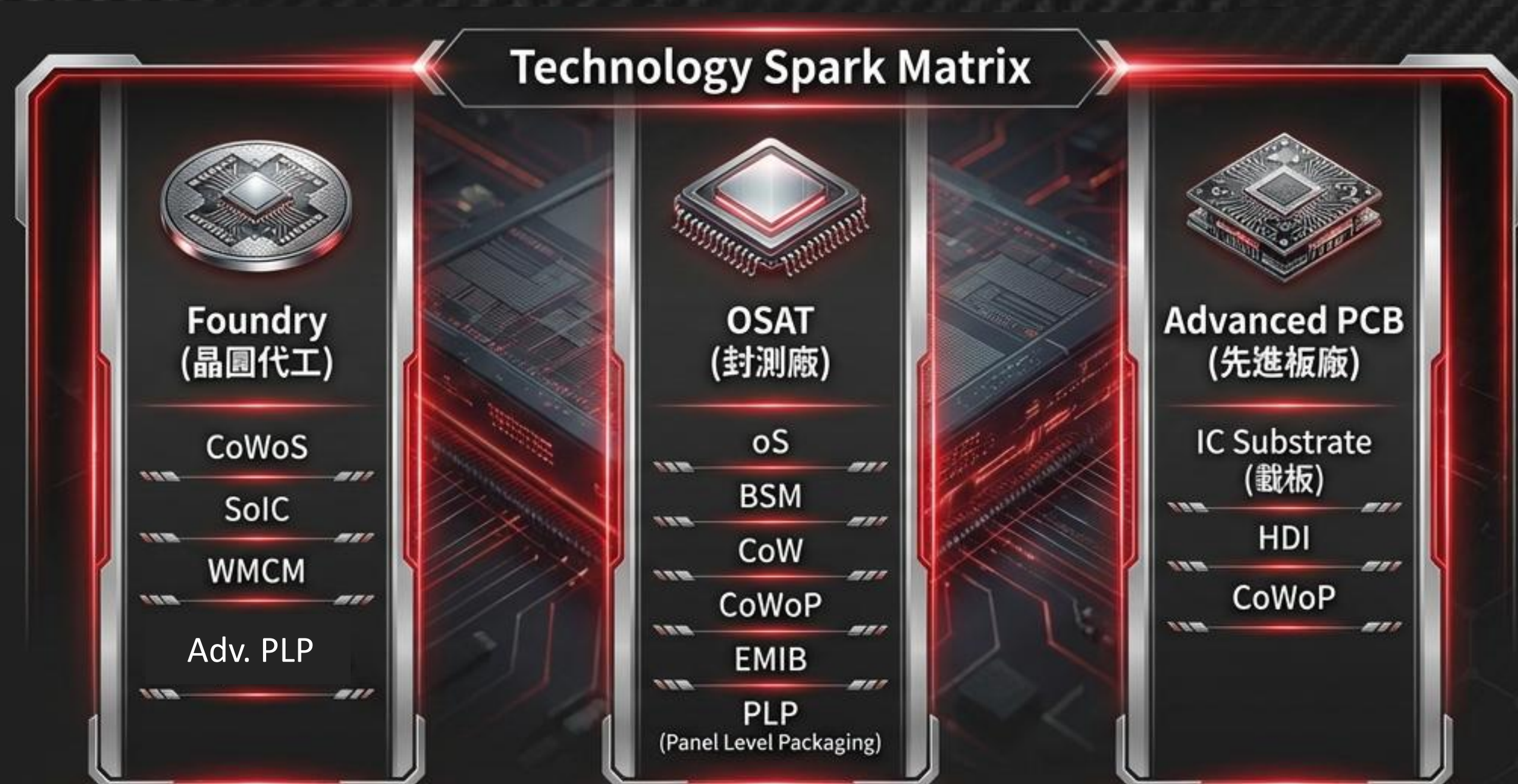
ENGINE I:
FOUNDRY 2.0 GLOBALIZATION
THE GLOBALIZED FOUNDRY TRACK

ENGINE II:
AI-DRIVEN PROCESS
DIVERSIFICATION.
THE AI PROCESS TRACK

ENGINE III:
ADVANCED PCB
& REGIONAL SHIFT.
THE IC SUBSTRATE PCB TRACK



Technology Roadmap: Full Spectrum Coverage



Not only capitalizing on current advanced packaging dividends, but already positioned for future new process demands over the next 3 years.

Building the Nest: R&D Center & Global Expansion

NT\$ 1.82 Billion

Establishing an R&D center to enable the development of diversified next-generation equipment.



USA

台中水湳研發中心
(Taichung Shuinan R&D Center)

The Innovation Hub

精科二廠
(Jingke Plant 2)

Capacity Expansion

Japan

NT\$ 1.48 Billion

Heavy investment in plants and facilities to ensure capacity security for the next 5 years.

F1 ADVANCED PACKAGING GRAND PRIX

Foundry Main Track
CoWoS / SoIC / WMCM



OSAT Track

PLP / oS / Bumping / CoW / EMIB



AI Substrate & HDI Track
IC Substrate / HDI



Unimicron Zhen Ding